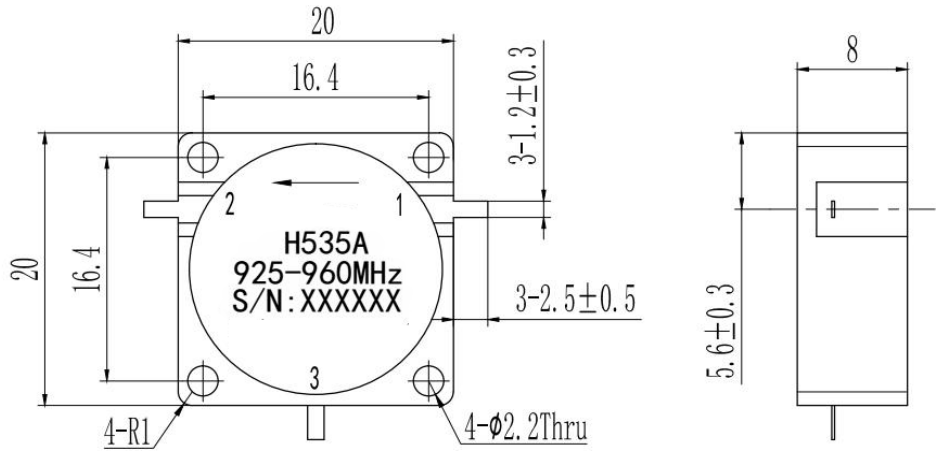
1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H535A [825-835]MHz	0.825	0.835	0.8300	0.010	23	0.25	1.15	150	
H535A [840-845]MHz	0.840	0.845	0.8425	0.005	23	0.25	1.15	150	
H535A [860-960]MHz	0.860	0.960	0.9100	0.100	23	0.3	1.15	100	
H535A [880-915]MHz	0.880	0.915	0.8975	0.035	23	0.25	1.15	150	
H535A [925-960]MHz	0.925	0.960	0.9425	0.350	23	0.3	1.15	100	-74
H535A [960-980]MHz	0.960	0.980	0.9700	0.020	23	0.3	1.15	100	
H535A [1150-1250]MHz	1.150	1.250	1.200	0.200	23	0.25	1.15	100	
H535A [1400-1610]MHz	1.400	1.610	1.505	0.210	22	0.3	1.2	100	
H535A [1750-2120]MHz	1.750	2.120	1.925	0.370	20	0.35	1.2	150	
H535A [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	150	
H535A [1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.25	1.15	100	
H535A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	100	
H535A [2300-2400]MHz	2.300	2.400	2.350	0.100	22	0.3	1.2	150	
H535A [2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.25	1.2	150	
H535A [2500-2700]MHz	2.500	2.700	2.600	0.200	22	0.28	1.17	150	